

What is Claimed is:

1. A production method of a multilayer ceramic capacitor, comprising the steps of:

firing a green chip to be a capacitor element body comprising dielectric layers and internal electrode layers in a reducing atmosphere; and

performing heat processing under an atmosphere of which oxygen partial pressure is higher than the reducing atmosphere;

wherein:

an average particle diameter (R), in a direction parallel with the internal electrode layers, in dielectric particles constituting said dielectric layer is made to be larger than a thickness (d) of said dielectric layer.

2. The production method of a multilayer ceramic capacitor as set forth in claim 1, wherein a temperature of heat processing after firing under said reducing atmosphere is 1000°C or more.

3. The production method of a multilayer ceramic capacitor as set forth in claim 1, wherein an oxygen partial pressure at the time of heat processing after firing under said reducing atmosphere is  $10^{-3}$  Pa to 1 Pa.

4. The production method of a multilayer ceramic capacitor as set forth in claim 2, wherein an oxygen partial pressure at the time of heat processing after firing under said reducing atmosphere is  $10^{-3}$  Pa to 1 Pa.